

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT										
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Wook-Seong Lee</td> <td>07/16/2007</td> </tr> <tr> <td>Young-Joon Baik</td> <td>07/16/2007</td> </tr> <tr> <td>Jeung-Hyun Jeong</td> <td>07/16/2007</td> </tr> <tr> <td>Ki-Woong Chae</td> <td>07/16/2007</td> </tr> </tbody> </table>		Name	Execution Date	Wook-Seong Lee	07/16/2007	Young-Joon Baik	07/16/2007	Jeung-Hyun Jeong	07/16/2007	Ki-Woong Chae	07/16/2007
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Ki-Woong Chae	07/16/2007										
<b>RECEIVING PARTY DATA</b>											
<b>Name:</b>	Korea Institute of Science and Technology										
<b>Street Address:</b>	39-1, Hawolgok-Dong, Sungbook-Gu										
<b>City:</b>	Seoul										
<b>State/Country:</b>	KOREA, REPUBLIC OF										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11833679</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11833679						
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Application Number:	11833679										
<b>CORRESPONDENCE DATA</b>											
<b>Fax Number:</b>	(212)382-0888										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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<b>Correspondent Name:</b>	Ostrolenk, Faber, Gerb & Soffen, LLP										
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<b>ATTORNEY DOCKET NUMBER:</b>	P/2292-125 (V4809)										
<b>NAME OF SUBMITTER:</b>	Max Moskowitz										
<b>Total Attachments: 1</b> source=00857532#page1.tif											

OP \$40.00 11833679

WHEREAS, I (We), Wook-Seong LEE & Young-Joon BAIK & Jeung-Hyun JEONG & Ki-Woong CHAE  
as assigner(s), have invented certain  
improvements in DC PLASMA ASSISTED CHEMICAL VAPOR DEPOSITION APPARATUS IN THE ABSENCE OF POSITIVE  
COLUMN, METHOD FOR DEPOSITING MATERIAL IN THE ABSENCE OF POSITIVE COLUMN, AND DIAMOND  
THIN LAYER THEREBY for which an application for United States Letters Patent has  
been executed by me (us) of even date herewith; and

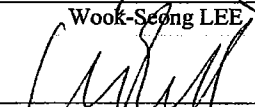
WHEREAS, Korea Institute of Science and Technology  
39-1, Hawolgok-Dong, Sungbook-Gu, Seoul, Korea as assignee, is desirous of  
acquiring all right, title and interest in and to said invention and any patent that may  
be granted therefor.

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and  
valuable consideration, the receipt of which is hereby acknowledged, I (we), as  
assignor(s), hereby sell, assign and set over to said assignee the entire right, title  
and interest for the United States and all other countries in and to said invention and  
the aforesaid application for Patent, all original, divisional, continuation, substitute  
or reissue applications and patents applied for or granted therefor in the United States  
and all other countries, including all rights of priority from the filing of said  
application, and all rights for past infringement, and the Commissioner of Patents and  
Trademarks is hereby authorized and requested to issue all patents on said inventions or  
resulting therefrom to said assignee herein, as assignee of the entire interest therein;  
and the undersigned for myself (ourselves) and my (our) legal representatives, heirs and  
assigns do hereby agree and covenant without further remuneration, to execute and deliver  
all divisional, continuation, reissue and other applications for Patent on said  
inventions and all assignments thereof to said assignee or its assigns, to communicate to  
said assignee or its representatives all facts known to the undersigned respecting said  
inventions, whenever requested, to testify in any interferences or other legal  
proceedings in which any of said applications or patents may become involved, to sign all  
lawful papers, make all rightful oaths, and to do generally everything necessary to  
assist assignee, its successors, assigns and nominees to obtain patent protection for  
said invention in the United States and all other countries, the expenses incident to  
said applications to be borne and paid by said assignee.

Date: 16, July, 2007

  
\_\_\_\_\_  
Wook-Seong LEE

Date: 16. July 2007

  
\_\_\_\_\_  
Young-Joon BAIK

Date: 16. July 2007

  
\_\_\_\_\_  
Jeung-Hyun JEONG

Date: 16 July 2007

  
\_\_\_\_\_  
Ki-Woong CHAE

Date: \_\_\_\_\_

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Date: \_\_\_\_\_

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LEGALIZATION RECOMMENDED